






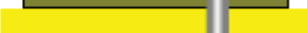




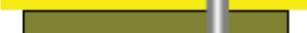







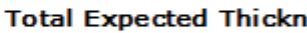


Job: 16626  
Revision: 1  
Engr: khill

Customer: Analog Devices, Inc.  
Part No.: 16626  
Part Rev:

Laminate Type Rogers Theta  
Minimum Tg 170  
Min Td 300  
MOT 0  
PLC Code 0  
T260 Min 0  
T288 Min 0  
Slash Sheet  
Laminate Color Natural

Layer	Thickness (Inch)	Stackup Picture	Family	Description	Type
compmask	0.0010		SM-Std	SM-Std	
compside	0.0019		Cu-Std	.5 + Std	comp - Cu-Std
	0.0070		Theta	1501	
layer2	0.0006		Cu-Std	.5	plane_t
	0.0040		Theta	.004	
layer3	0.0006		Cu-Std	.5	plane_b
	0.0046		Theta	3313	
layer4	0.0006		Cu-Std	.5	plane_t
	0.0100		Theta	.010	
layer5	0.0006		Cu-Std	.5	plane_b
	0.0046		Theta	3313	
layer6	0.0006		Cu-Std	.5	signal_t
	0.0100		Theta	.010	
layer7	0.0006		Cu-Std	.5	plane_b
	0.0046		Theta	3313	
layer8	0.0006		Cu-Std	.5	plane_t
	0.0040		Theta	.004	
layer9	0.0006		Cu-Std	.5	plane_b
	0.0070		Theta	1501	
solderside	0.0019		Cu-Std	.5 + Std	solder - Cu-Std
soldermask	0.0010		SM-Std	SM-Std	
<b>0.0665</b>		<b>Total Expected Thickness</b>			
<b>0.0580</b>		<b>After Lamination</b>		<b>+0.0040</b>	<b>-0.0040</b>

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### Requirements Information in Inch

Top Layer	Bottom Layer	Required Thickness	Tol +	Tol -	Calculated Thickness
Incl.Plating		0.0620	0.0050	0.0050	0.0645
After Lamination		0.0580	0.0040	0.0040	0.0619

### Comments

### Concise Impedance Constraint Information Line Widths inInch

#	Impedance Type Name	Type Picture	Aff Layer	Designed Width	Edited Width	Cntr to Cntr	Ref Planes	Target ohms	Predicted ohms
1	Surface MS		compside None	0.012	0.012		None layer2	50 +/- 5.0	
2	Surface MS		solderside None	0.012	0.012		None layer9	50 +/- 5.0	